10/520493

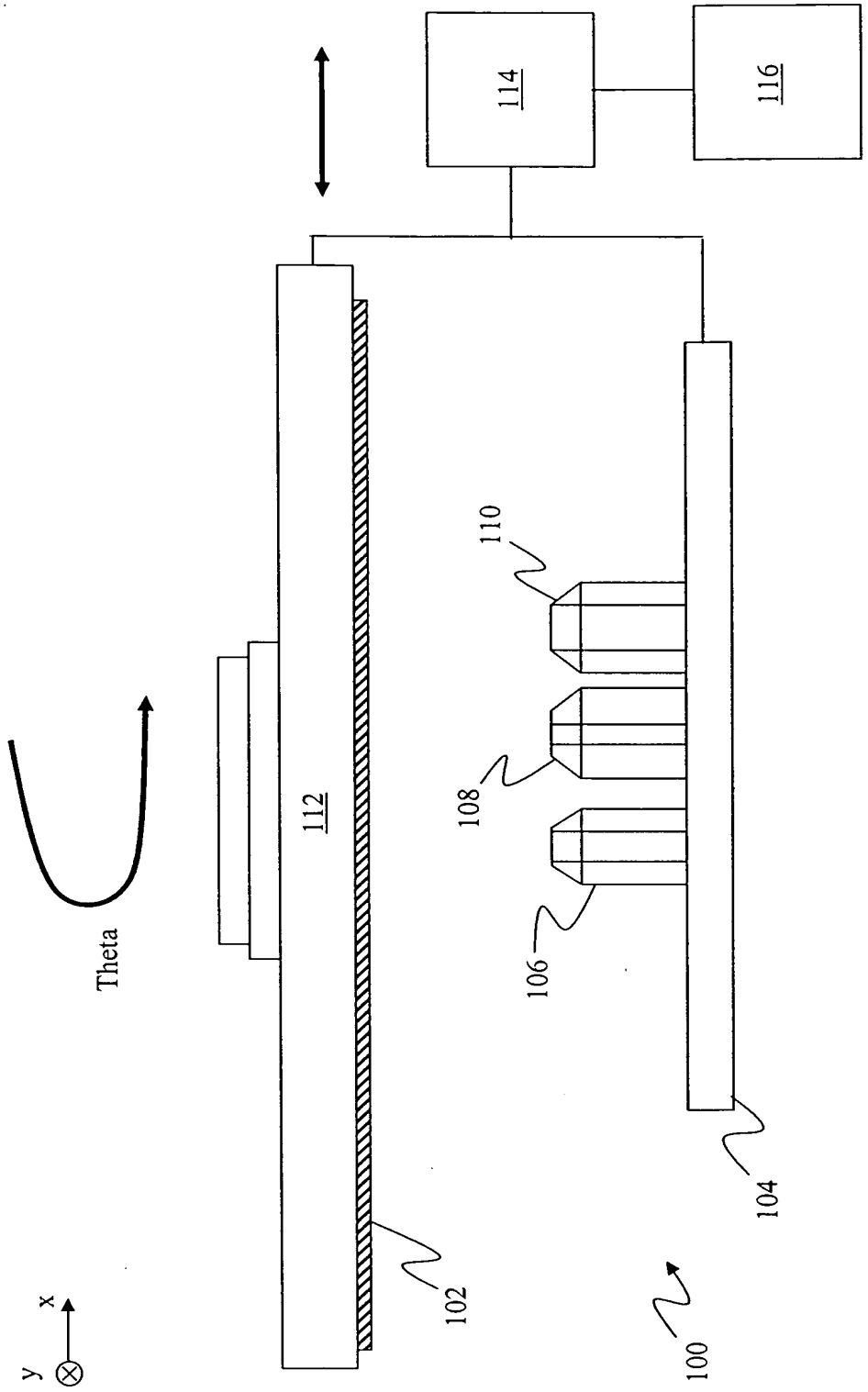

Fig. 1

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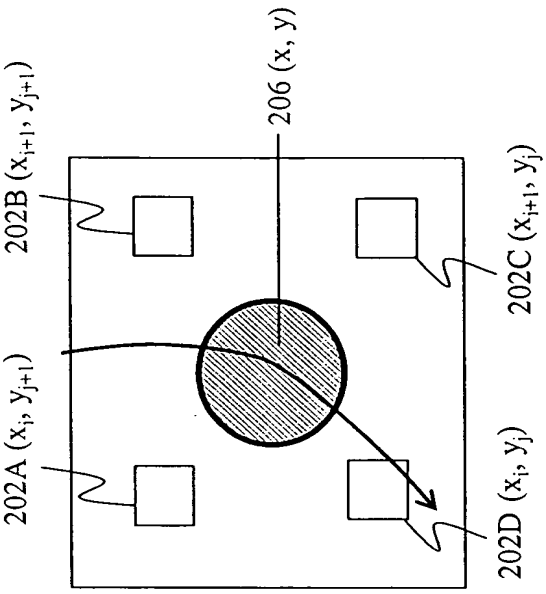

Fig. 2B

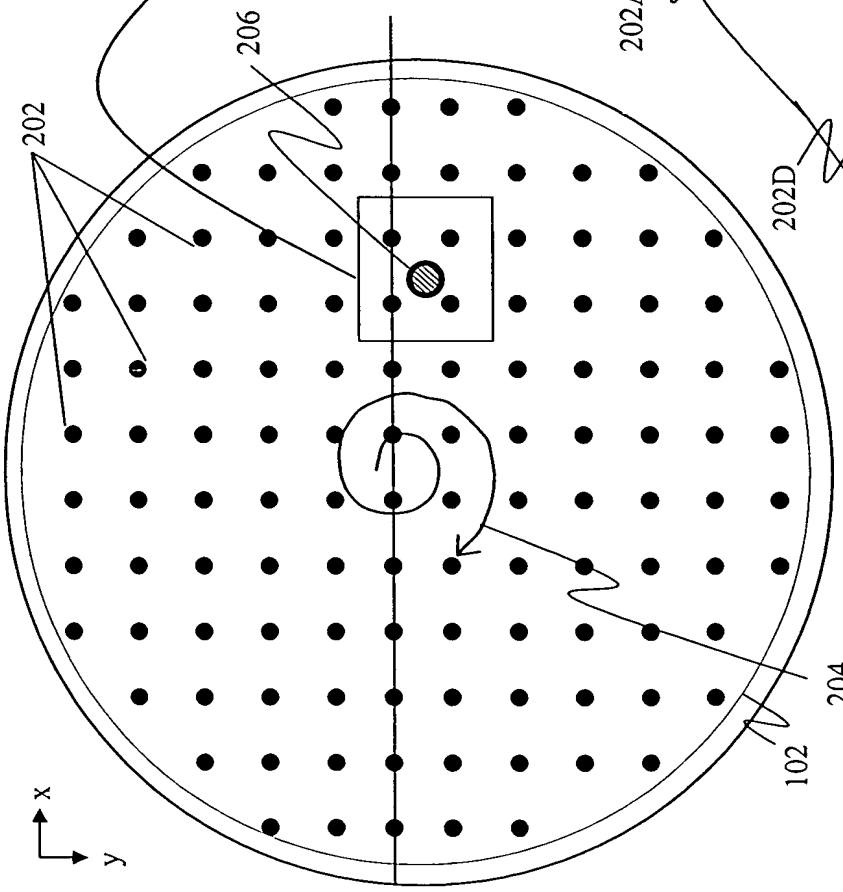

Fig. 2A

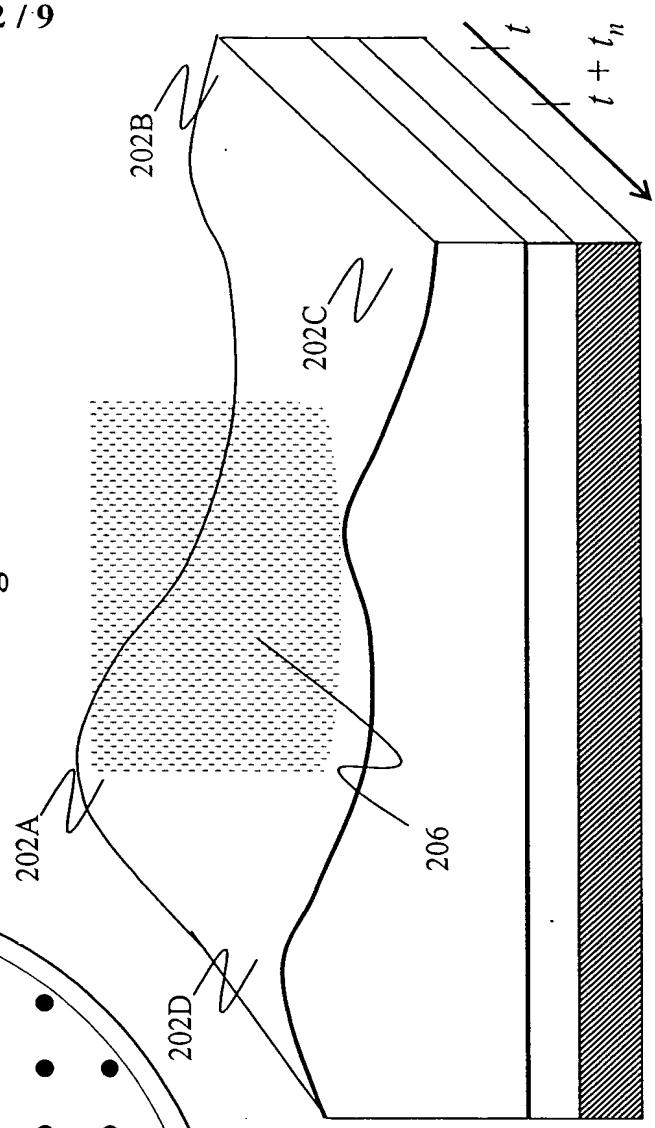

Fig. 2C

10/520492

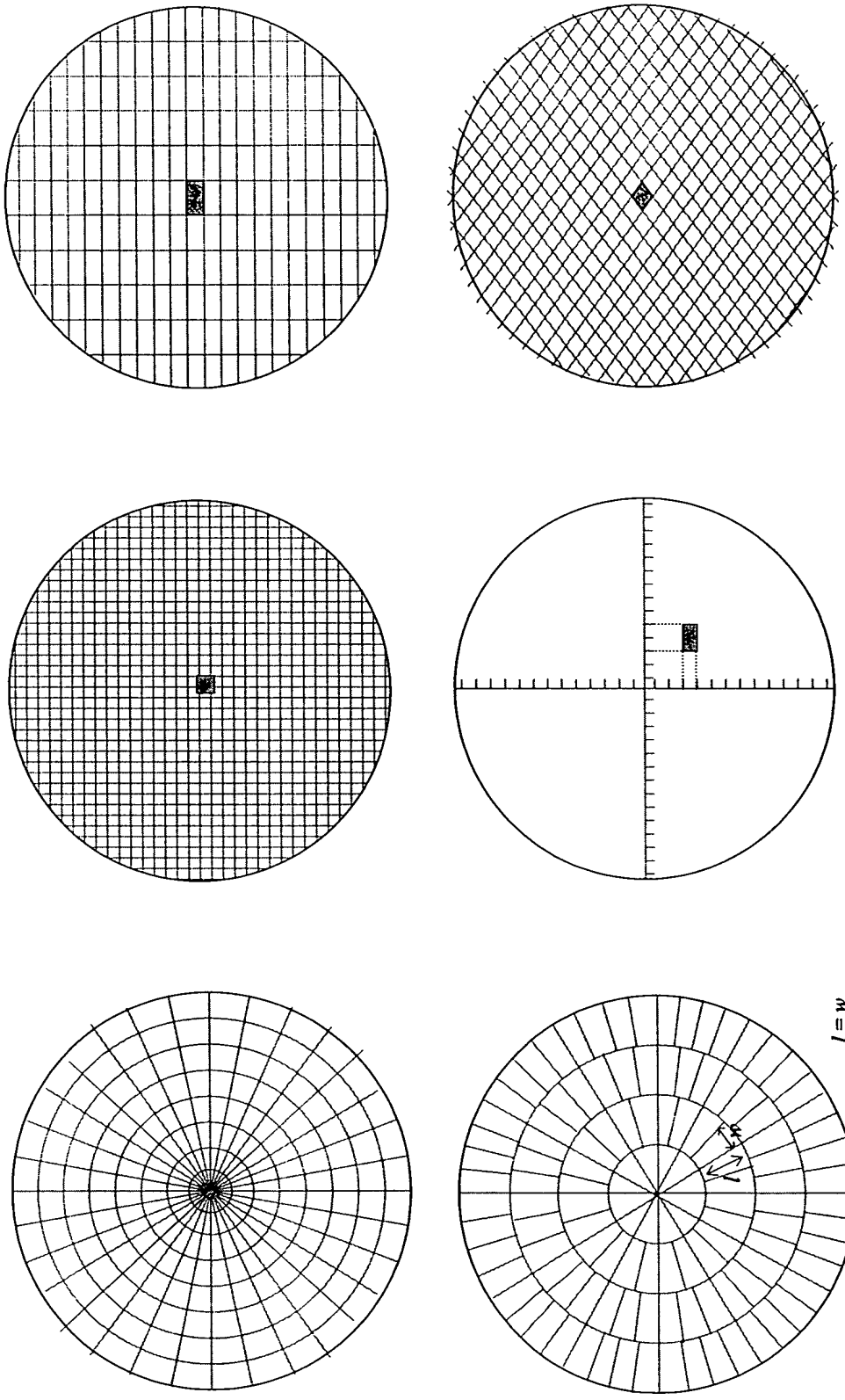

Fig. 3

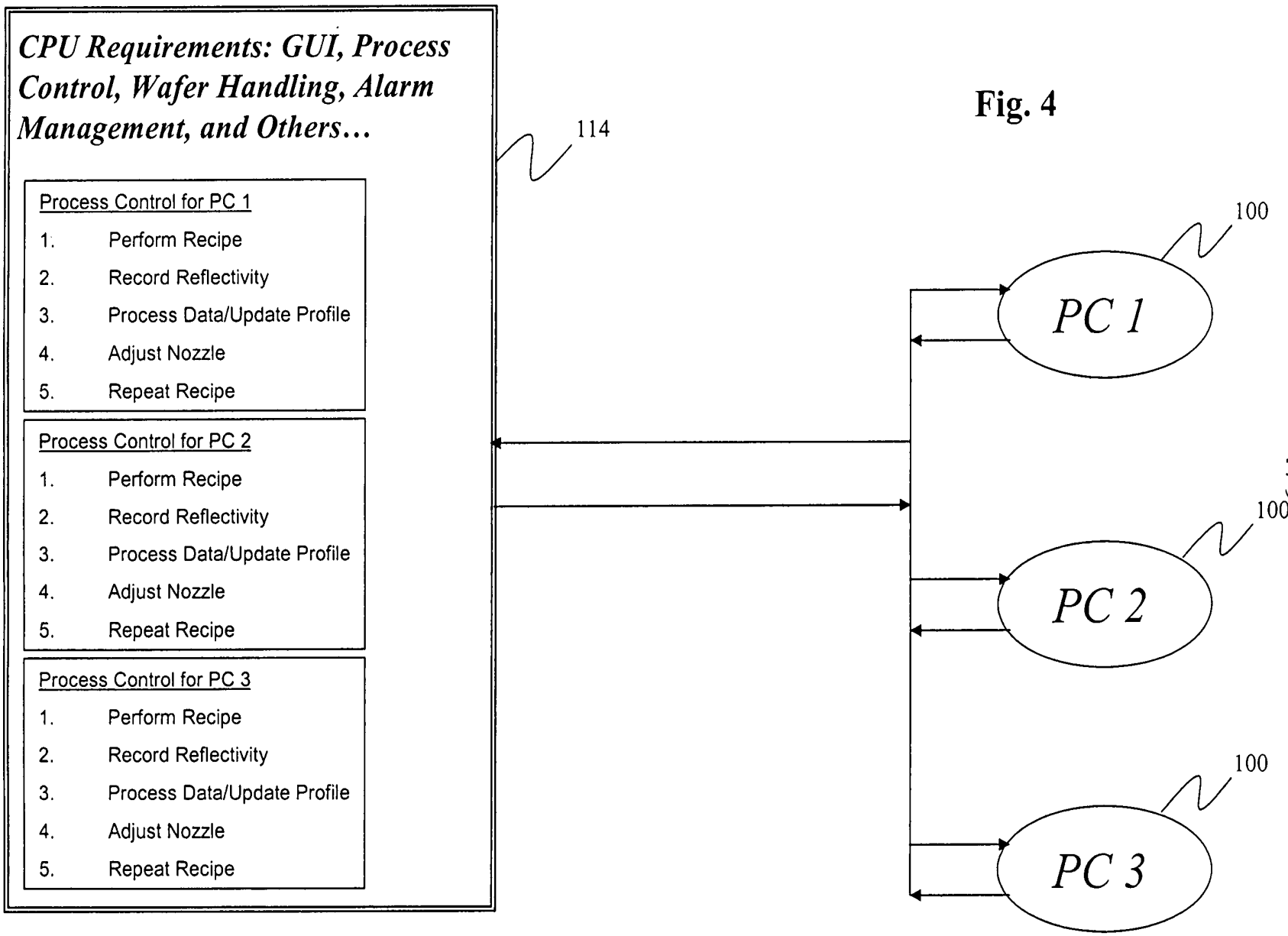

Fig. 4

Title: ADAPTIVE ELECTROPOLISHING USING THICKNESS MEASUREMENTS AND et al.
Inventor: Hui WANG et al.
Application No.: Not Yet Assigned
Docket No.:495152002100
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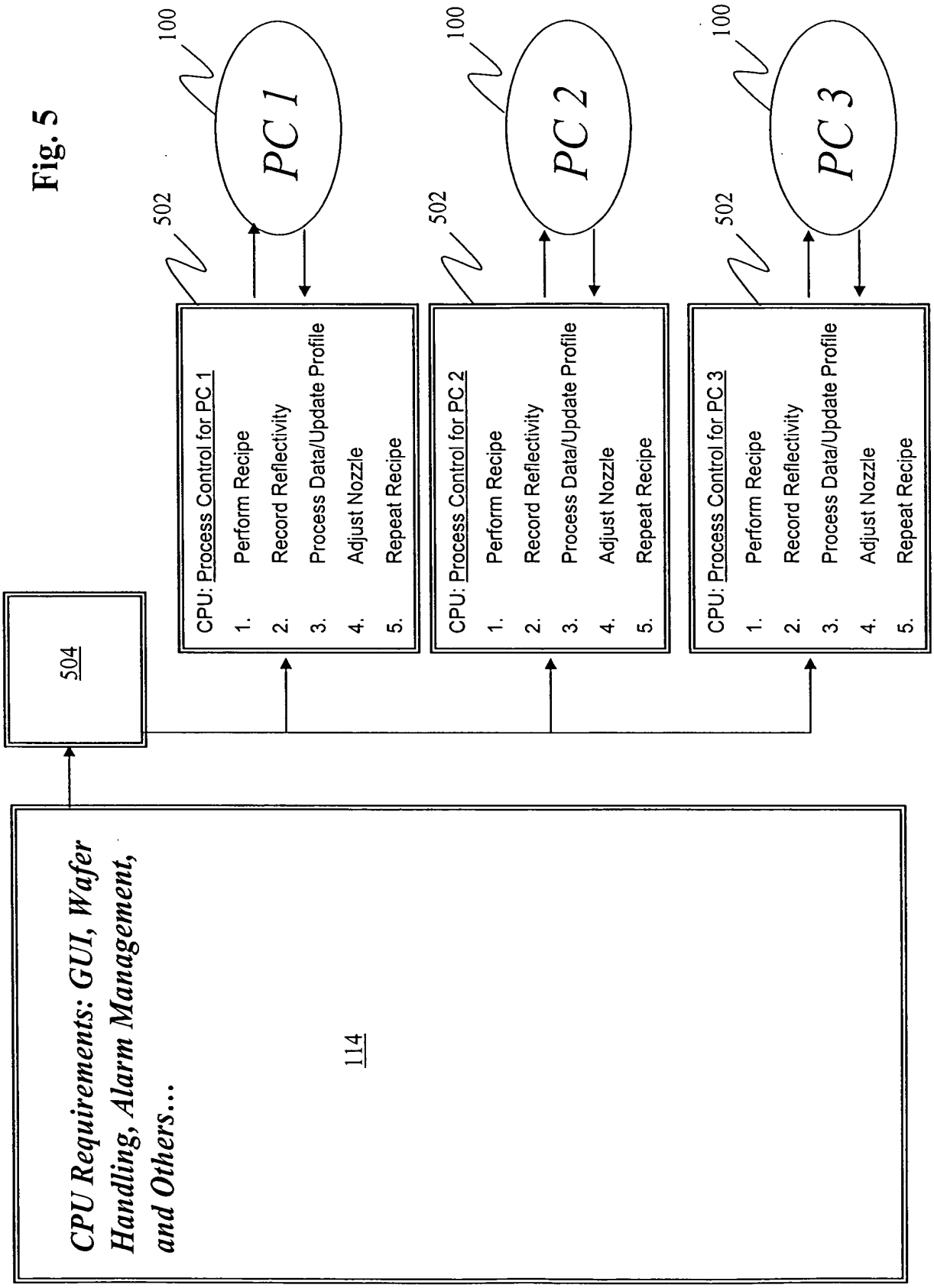
Fig. 5


CPU Requirements: GUI, Wafer Handling, Alarm Management, and Others...
114
504
100
PC 1
502
CPU: Process Control for PC 1
1. Perform Recipe
2. Record Reflectivity
3. Process Data/Update Profile
4. Adjust Nozzle
5. Repeat Recipe
100
PC 2
502
CPU: Process Control for PC 2
1. Perform Recipe
2. Record Reflectivity
3. Process Data/Update Profile
4. Adjust Nozzle
5. Repeat Recipe
100
PC 3
502
CPU: Process Control for PC 3
1. Perform Recipe
2. Record Reflectivity
3. Process Data/Update Profile
4. Adjust Nozzle
5. Repeat Recipe

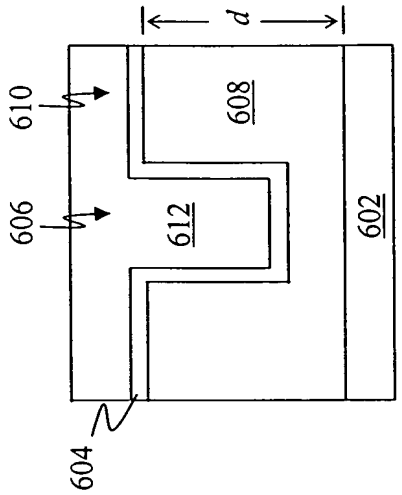


Fig. 6B

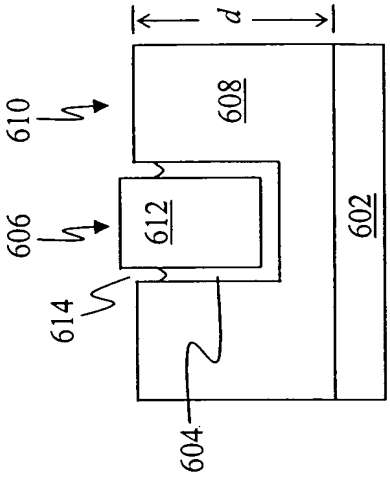


Fig. 6D

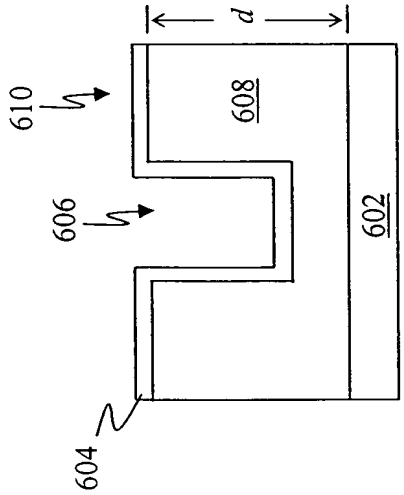


Fig. 6A

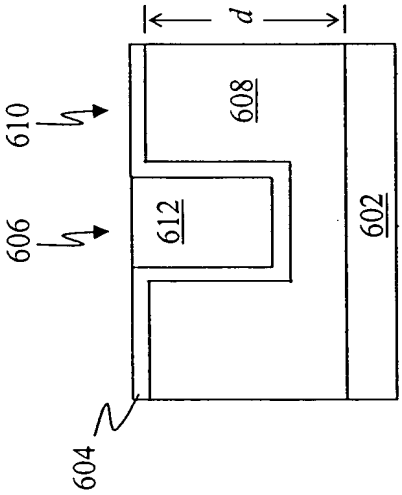


Fig. 6C

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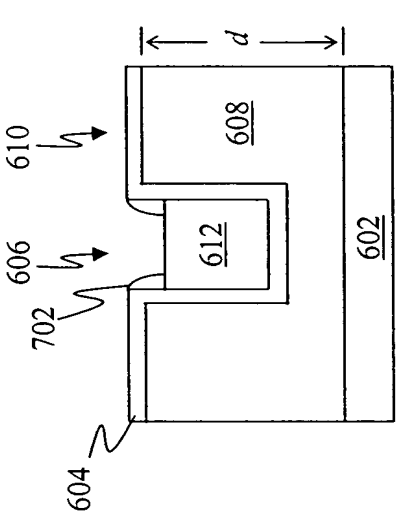

Fig. 7B

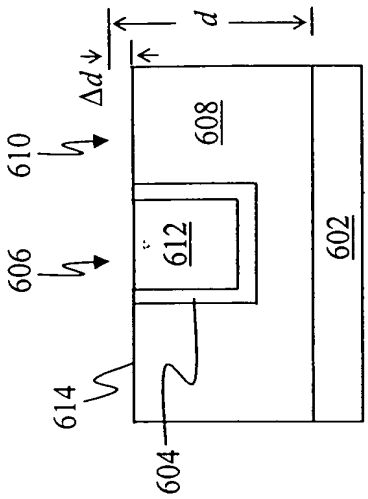

Fig. 7D

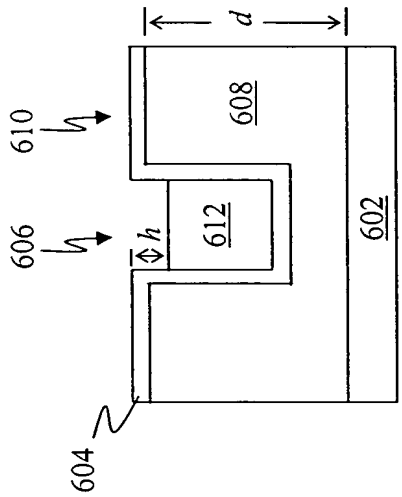

Fig. 7A

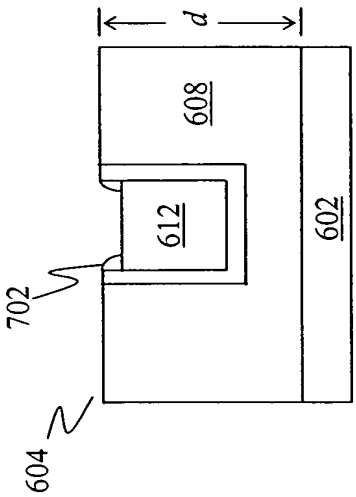

Fig. 7C

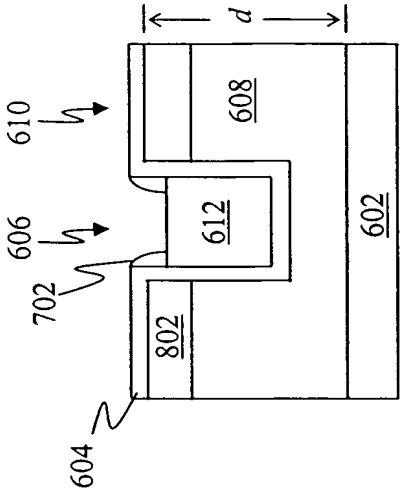

Fig. 8B

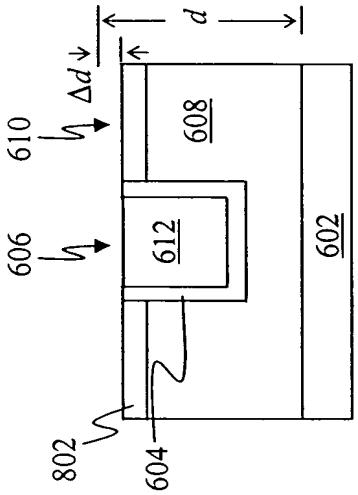

Fig. 8D

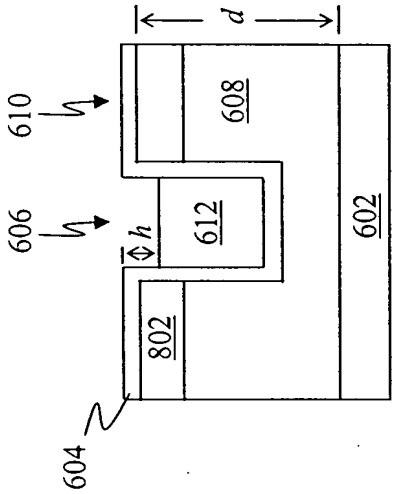

Fig. 8A

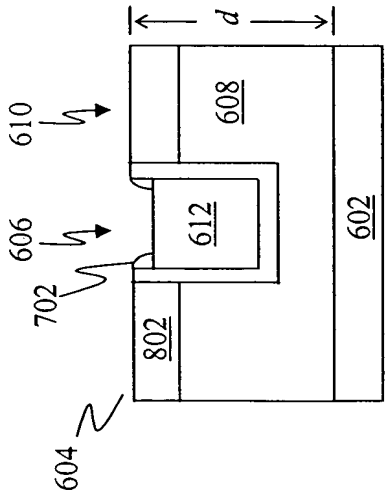

Fig. 8C

10/520493

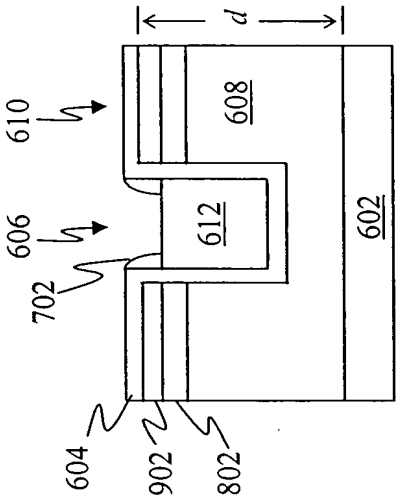

Fig. 9B

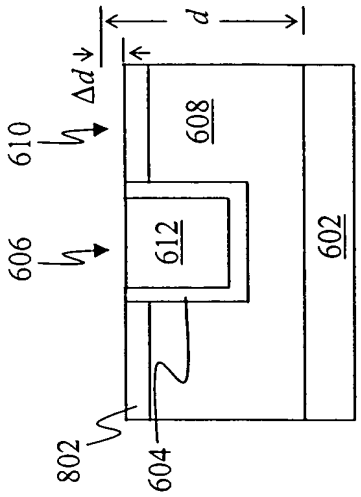

Fig. 9D

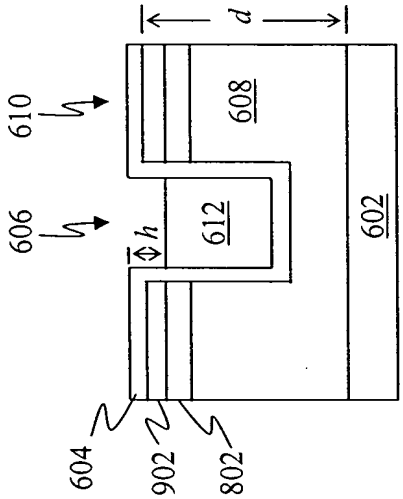

Fig. 9A

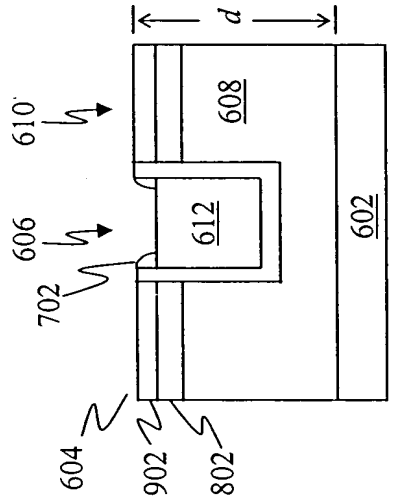

Fig. 9C